POWER® ULTRAMICRO POWERSYSTEM (2.00 mm) .0787" PITCH







UMPT/UMPS compared to another small form factor power solution

mPower*

FEATURES & BENEFITS

- Up to 18 A per blade (1 blade powered)
- Design flexibility as a power-only system or a two-piece system for power/signal applications
- Use with Samtec's high-speed connector systems for a unique power/signal system
- Choice of 2 to 10 positions
- 5 mm to 20 mm stack heights available
- Tin or 10 µ" Gold plated power blades; 30 µ" Gold plating available to meet specific regulations
- Optional weld tabs
- Cable-to-board and cable-to-cable systems in development

•—— Traditional Power Solutions

CREEPAGE & CLEARANCE

UMPT/UMPS					
CREEPAGE	2.20 mm				
CLEARANCE	1.65 mm				

Selectively loading contacts achieves customer specific creepage and clearance requirements.

KEY SPECIFICATIONS

РІТСН	STACK HEIGHTS	INSULATOR MATERIAL	CONTACT MATERIAL	PLATING	OPERATING TEMP RANGE	VOLTAGE RATING	LEAD-FREE SOLDERABLE
2.00 mm	5 to 16, 18, 20 mm	Black LCP	Copper Alloy	Sn or Au over 50 μ" (1.27 μm) Ni	-55 °C to +105 °C with Tin -55 °C to +125 °C with Gold	460 VAC/ 650 VDC	Yes

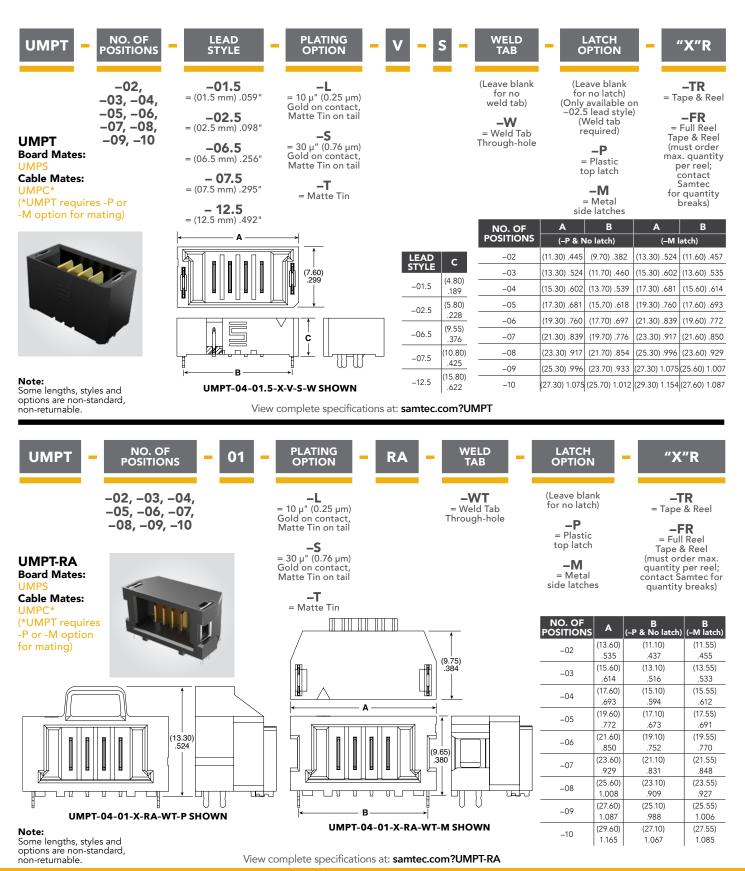
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ULTRA MICRO POWER TERMINAL



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